

## ■ DESCRIPTION

The SMC3056 is the N-Channel logic enhancement mode power field effect transistor is produced using high cell density advanced trench technology to provide excellent  $R_{DS(ON)}$ .low gate charge and operation gate as 1.8V.

This device is suitable for use as a load switch or other general applications.

*SMC3056K-TRG ROHS Compliant This is Halogen Free*

*20V N-Channel Enhancement Mode MOSFET*

## ■ FEATURE

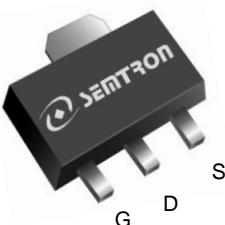
- ◆  $20V/6.0A, R_{DS(ON)}=22m\Omega(\text{typ.}) @ V_{GS}=4.5V$
- ◆  $20V/4.0A, R_{DS(ON)}=27m\Omega(\text{typ.}) @ V_{GS}=2.5V$
- ◆  $20V/2.8A, R_{DS(ON)}=35m\Omega(\text{typ.}) @ V_{GS}=1.8V$
- ◆ Super high density cell design for extremely low  $R_{DS(ON)}$
- ◆ Exceptional on-resistance and Maximum DC current capability

## ■ APPLICATIONS

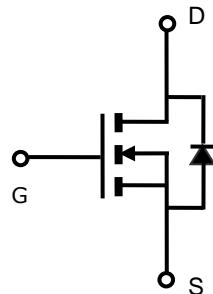
- ◆ Power Management in Note book
- ◆ Portable Equipment
- ◆ DSC
- ◆ LCD Display inverter
- ◆ Battery Powered System



## ■ PIN CONFIGURATION



SOT-89  
Top View



## ■ PART NUMBER INFORMATION

<b>SMC 3056 K – TR G</b> a   b   c   d   e	<small>a : Company name.              b : Product Serial number.              c : Package code              d : Handling code              e : Green produce code</small>
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## ■ ORDERING INFORMATION

Part Number	Package Code	Handling Code	Shipping
SMC3056K-TRG	K : SOT-89	TR : Tape&Reel	1K/Reel

※ Year Code : 0 ~ 9, 2010 : 0

※ Week Code : A(1~2) ~ Z(53~54)

※ SOT-89 : Only available in tape and reel packaging.

## ■ ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless otherwise noted )

Symbol	Parameter	Typical	Unit
$V_{DSS}$	Drain-Source Voltage	20	V
$V_{GSS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current ( $T_c=25^\circ C$ ) <sup>A</sup>	6.0	A
	Continuous Drain Current ( $T_c=70^\circ C$ ) <sup>A</sup>		
$I_{DM}$	Pulsed Drain Current <sup>B</sup>	14	A
$P_D$	Power Dissipation	$T_A=25^\circ C$ $T_A=70^\circ C$	2.5 1.2
$T_J$	Operation Junction Temperature	-55 to 150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

## ■ THERMAL DATA

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient <sup>A</sup>	Steady-State	-	$^\circ C/W$
$R_{\theta JL}$	Thermal Resistance Junction to Lead <sup>A</sup>	Steady-State	-	$^\circ C/W$

**ELECTRICAL CHARACTERISTICS( $T_J = 25^\circ\text{C}$  Unless otherwise noted)**

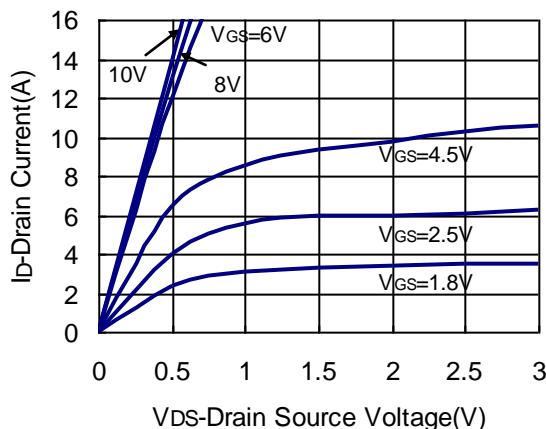
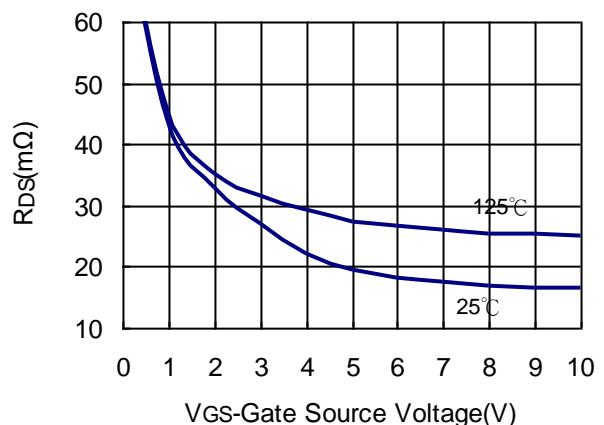
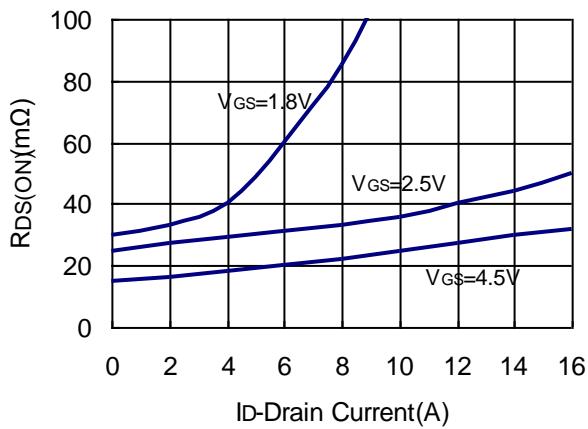
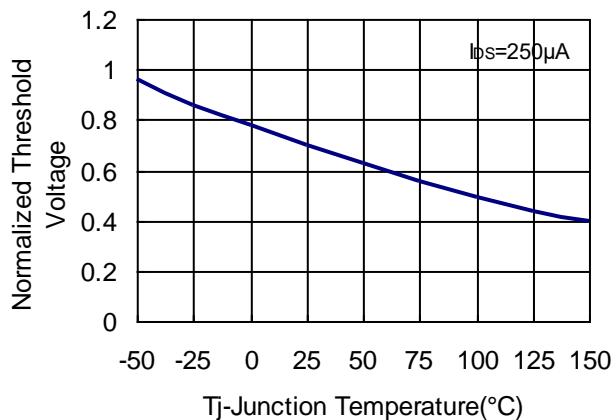
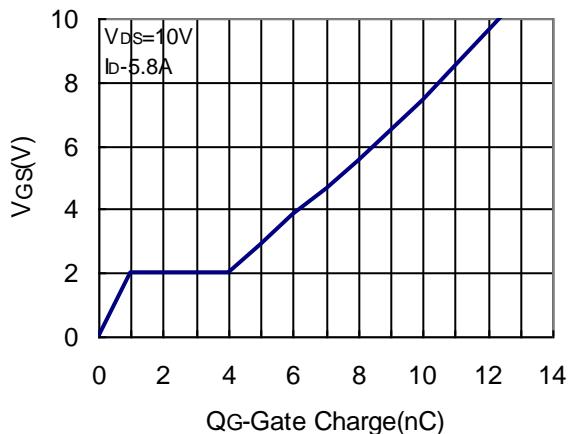
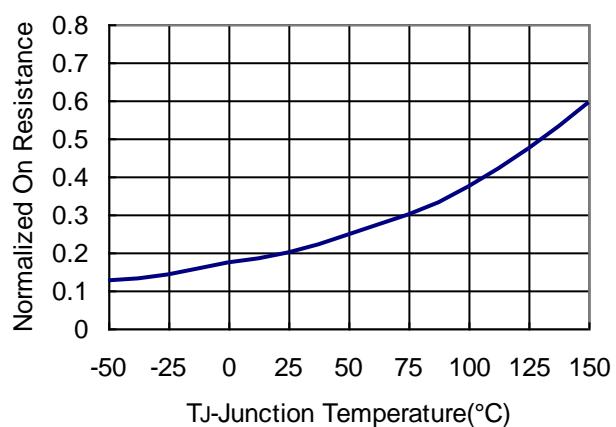
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
<b>Static Parameters</b>							
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.5		1.0	V	
$I_{GS}$	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			$\pm 100$	nA	
$I_{DS}$	Zero Gate Voltage, Drain-Source Leakage Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$ $T_J=25^\circ\text{C}$			1	$\mu\text{A}$	
		$V_{DS}=20\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			5		
$R_{DS(\text{ON})}$	Drain-source On-Resistance <sup>B</sup>	$V_{GS}=4.5\text{V}, I_D=6.0\text{A}$		22	27	$\text{m}\Omega$	
		$V_{GS}=2.5\text{V}, I_D=4.0\text{A}$		27	32		
		$V_{GS}=1.8\text{V}, I_D=2.8\text{A}$		35	45		
$G_f$	Forward Transconductance	$V_{DS}=15\text{V}, I_D=5.0\text{A}$		30		S	
<b>Source-Drain Diode</b>							
$V_{SD}$	Diode Forward Voltage	$I_S=1.7\text{A}, V_{GS}=0\text{V}$		0.6	1.2	V	
$I_S$	Continuous Source Current <sup>AD</sup>				6	A	
<b>Dynamic Parameters</b>							
$Q_g (4.5\text{V})$	Total Gate Charge	$V_{DS}=10\text{V}$ $V_{GS}=4.5\text{V}$ $I_D=5.8\text{A}$		7.7		nC	
$Q_{gs}$	Gate-Source Charge			1.1			
$Q_{gd}$	Gate-Drain Charge			2.35			
$C_{iss}$	Input Capacitance	$V_{DS}=10\text{V}$ $V_{GS}=0\text{V}$ $f=1\text{MHz}$		650		pF	
$C_{oss}$	Output Capacitance			92			
$C_{rss}$	Reverse Transfer Capacitance			75			
$t_{d(on)}$	Turn-On Time	$V_{DD}=10\text{V}$ $I_D=1.0\text{A}$ $V_{GEN}=4.5\text{V}$ $R_G=6\Omega$		19.1		nS	
$t_r$				135			
$t_{d(off)}$	Turn-Off Time			90			
$t_f$				116			

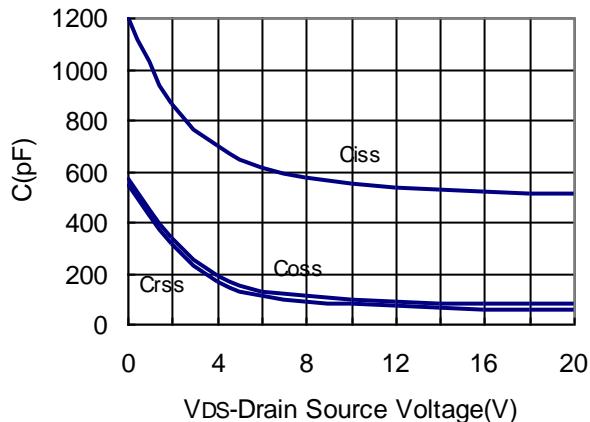
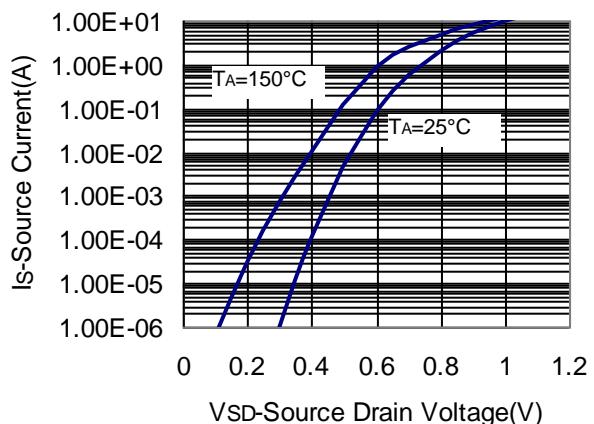
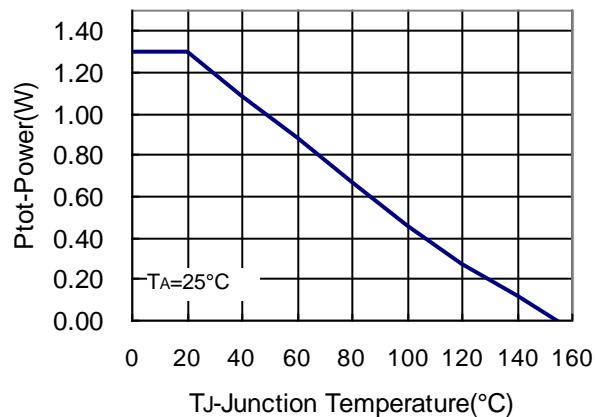
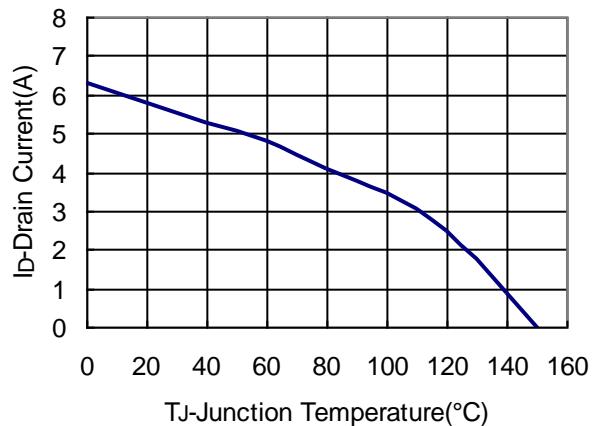
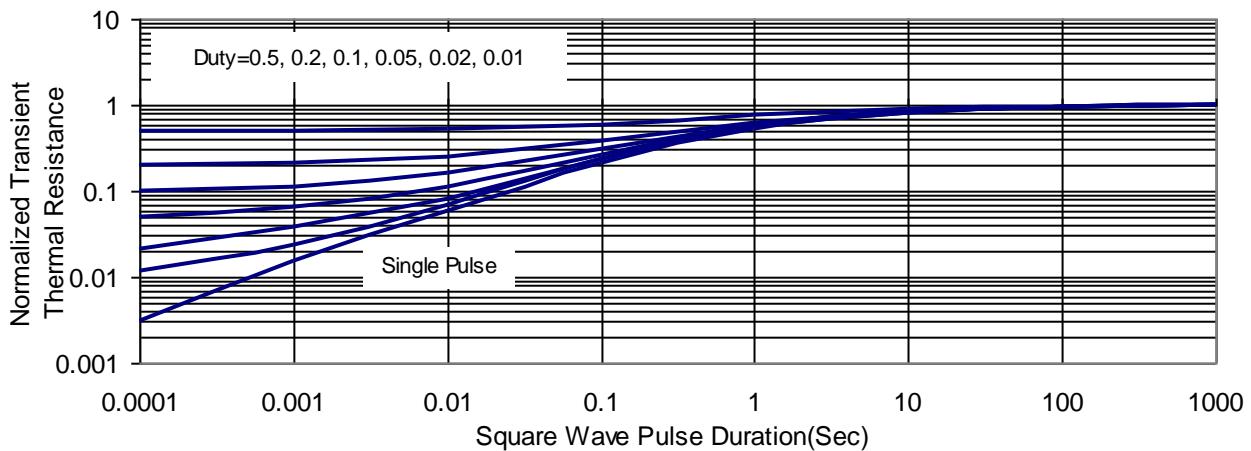
Note:

- A. The value of  $R_{DS}$  is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ .
- B. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- C. The EAS data shows Max. rating . The test condition is  $V_{DD}=20\text{V}, V_{GS}=10\text{V}, L=0.1\text{mH}$ .
- D. The data is theoretically the same as  $I_D$  and  $I_{DS}$  , in real applications , should be limited by total power dissipation.

The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date

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**TYPICAL CHARACTERISTICS (25°C Unless Note)**
**Output Characteristics**

**Drain-Source On Resistance**

**Drain Source On Resistance**

**Gate Threshold Voltage**

**Gate Charge**

**Drain Source On Resistance**


**TYPICAL CHARACTERISTICS (25°C Unless Note)**
**Capacitance**

**Source Drain Diode Forward**

**Power Dissipation**

**Drain Current**

**Thermal Transient Impedance**


## **SOT-89 PACKAGE DIMENSIONS**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.130	0.197
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 BSC		0.061 BSC	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.550 BSC		0.060 BSC	
e1	3.000 BSC		0.118 BSC	
L	0.900	1.200	0.035	0.047

